

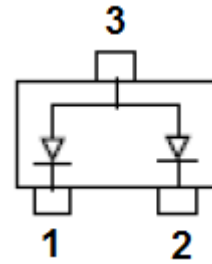
Features

- SOT-23 surface mount package
- 300mW power dissipation rating
- Ideally suited for automatic insertion
- ΔV_z for both diodes in one case is $\leq 2\%$
- Common cathode style available see DZ series
- ESD: >15KV
- Halogen free
- Qualified to AEC-Q101 standards for high reliability

HF

Mechanical Data

- Case: SOT-23
- Molding Compound, UL Flammability Classification Rating 94V-0
- Terminals: Tin Plated Leads, Solderable Per MIL-STD-202, Method 208



SOT-23

Ordering Information

Part Number	Package	Shipping	Marking Code
TAZ23BXX	SOT-23	3000 pcs / Tape & Reel	See Table on page2

Maximum Ratings (@ $T_A=25^\circ\text{C}$ unless otherwise specified)

Characteristic	Symbol	Value	Units
Power Dissipation	P_D	300	mW
Typical Thermal Resistance Per Leg	$R_{\theta JA}$	420	$^\circ\text{C/W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical Characteristics (@T_A=25°C unless otherwise specified)

Type Number	Marking Code	V _Z			Z _{zT}	Z _{zK}	T _c	Maximum Reverse Current	
		@I _{zT} =5mA			@I _{zT} =5mA	@I _{zT} =1mA	%/°C	I _R	V _R
		Nom(V)	Min(V)	Max(V)	Ω	Ω	TYP.	uA	V
TAZ23B2V4	D40	2.4	2.35	2.45	85	600	-0.065	100	1.0
TAZ23B2V7	D41	2.7	2.65	2.75	83	600	-0.065	75	1.0
TAZ23B3V0	D42	3.0	2.94	3.06	95	600	-0.060	50	1.0
TAZ23B3V3	D43	3.3	3.23	3.37	95	600	-0.055	25	1.0
TAZ23B3V6	D44	3.6	3.53	3.67	95	600	-0.055	15	1.0
TAZ23B3V9	D45	3.9	3.82	3.98	95	600	-0.050	10	1.0
TAZ23B4V3	D46	4.3	4.21	4.39	95	600	-0.035	5.0	1.0
TAZ23B4V7	D47	4.7	4.61	4.79	78	500	-0.015	5.0	2.0
TAZ23B5V1	D48	5.1	5.00	5.20	60	480	+0.005	0.1	0.8
TAZ23B5V6	D49	5.6	5.49	5.71	40	400	+0.020	0.1	1.0
TAZ23B6V2	D50	6.2	6.08	6.32	10	200	+0.030	0.1	2.0
TAZ23B6V8	D51	6.8	6.66	6.94	8	150	+0.045	0.1	3.0
TAZ23B7V5	D52	7.5	7.35	7.65	7	50	+0.050	0.1	5.0
TAZ23B8V2	D53	8.2	8.04	8.36	7	50	+0.055	0.1	6.0
TAZ23B9V1	D54	9.1	8.92	9.28	10	50	+0.065	0.1	7.0
TAZ23B10	D55	10	9.80	10.20	15	70	+0.065	0.1	7.5
TAZ23B11	D56	11	10.8	11.2	20	70	+0.070	0.1	8.5
TAZ23B12	D57	12	11.8	12.22	20	90	+0.075	0.1	9.0
TAZ23B13	D58	13	12.7	13.3	25	110	+0.080	0.1	10.0
TAZ23B15	D59	15	14.7	15.3	30	110	+0.080	0.1	11.0
TAZ23B16	D60	16	15.7	16.3	40	170	+0.090	0.1	12.0
TAZ23B18	D61	18	17.6	18.4	50	170	+0.090	0.1	14.0
TAZ23B20	D62	20	19.6	20.40	50	220	+0.090	0.1	15.0
TAZ23B22	D63	22	21.6	22.4	55	220	+0.090	0.1	17.0
TAZ23B24	D64	24	23.5	24.5	80	220	+0.090	0.1	18.0
TAZ23B27	D65	27	26.5	27.5	80	250	+0.090	0.1	20.0
TAZ23B30	D66	30	29.40	30.6	80	250	+0.090	0.1	22.5
TAZ23B33	D67	33	32.3	33.7	80	250	+0.090	0.1	25.0
TAZ23B36	D68	36	35.3	36.7	90	250	+0.090	0.1	27.0
TAZ23B39	D69	39	38.2	39.8	90	300	+0.110	0.1	29.0
TAZ23B43	D70	43	42.1	43.9	100	700	+0.110	0.1	32.0
TAZ23B47	D71	47	46.1	47.9	100	750	+0.110	0.1	35.0
TAZ23B51	D72	51	50	52	100	750	+0.110	0.1	38.0

TYPICAL CHARACTERISTICS @ $T_a=25^\circ\text{C}$ unless otherwise specified

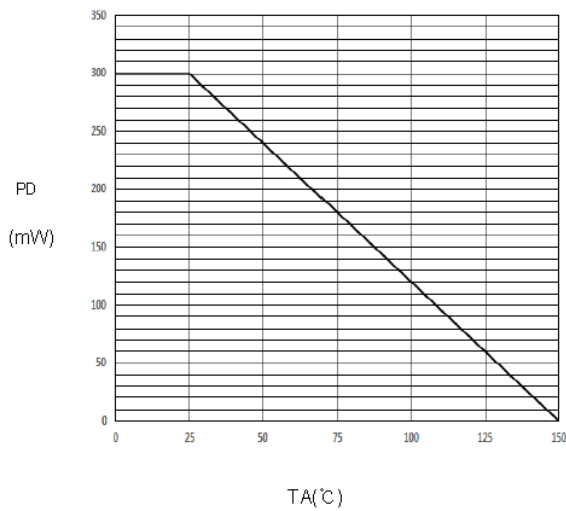


Fig 1. Per diode: Power Derating Curve

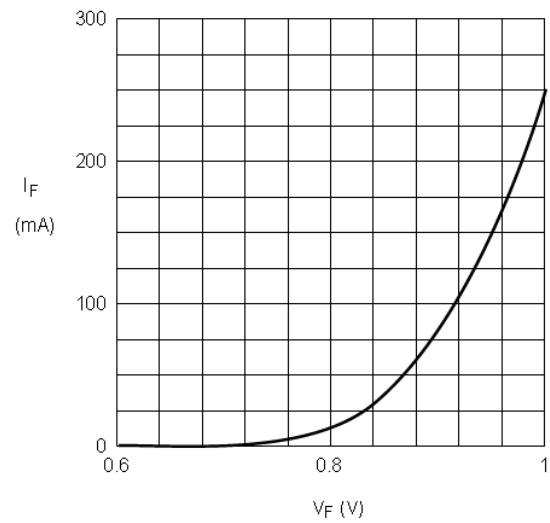


Fig 2. Per diode: Forward current as a function of forward voltage; typical values

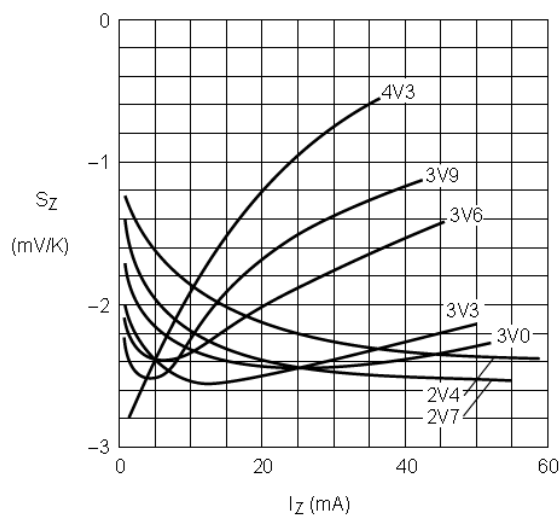


Fig 3. Per diode: Temperature coefficient as a function of working current; typical values

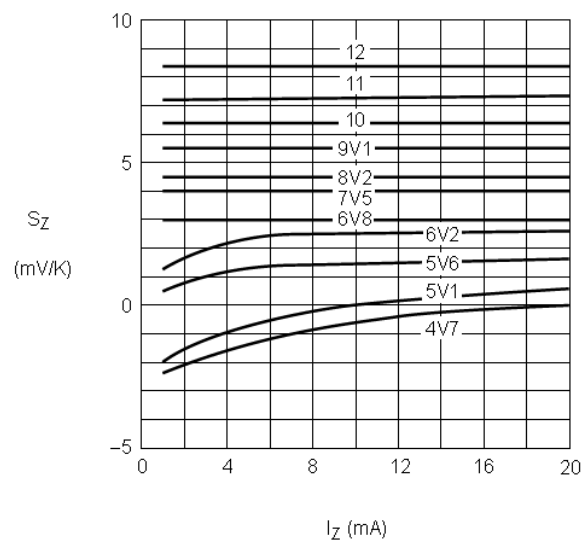
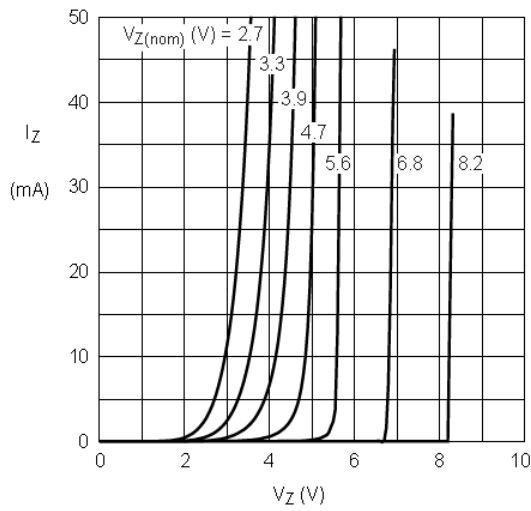
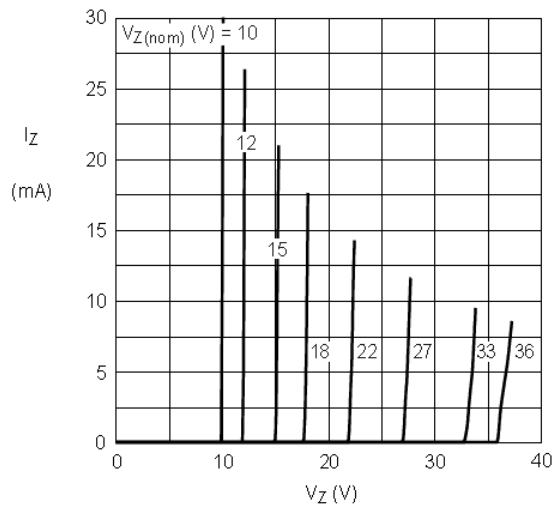


Fig 4. Per diode: Temperature coefficient as a function of working current; typical values



$T_j = 25^\circ\text{C}$
 AZ23B2V4 to AZ23B4V3

Fig 5. Per diode: Working current as a function of working voltage; typical values

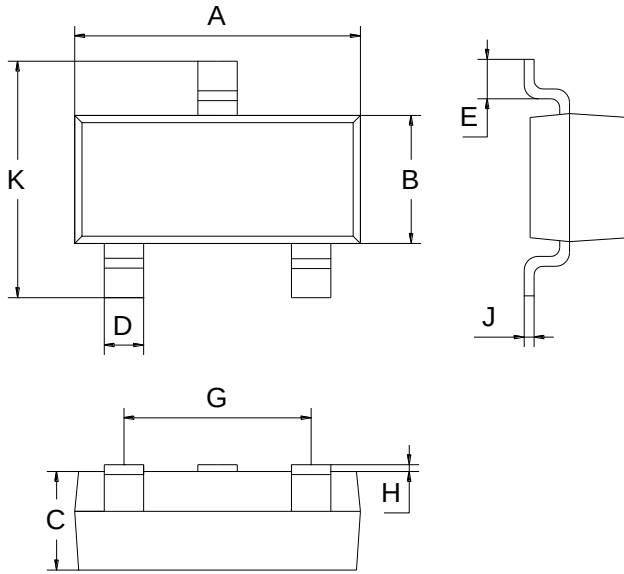


$T_j = 25^\circ\text{C}$
 AZ23B2V4 to AZ23B4V3

Fig 6. Per diode: Working current as a function of working voltage; typical values

Package Outline Dimensions(unit:mm)

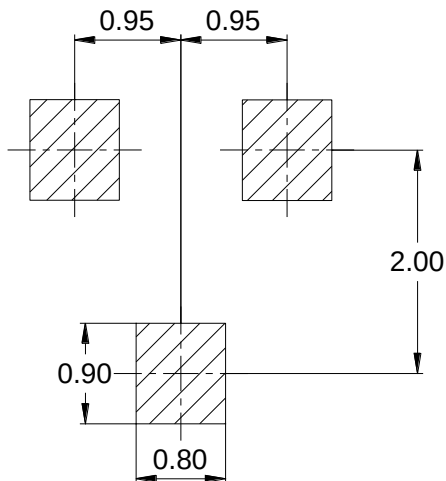
SOT-23



SOT-23		
Dim	Min	Max
A	2.70	3.10
B	1.10	1.50
C	0.90	1.10
D	0.30	0.50
E	0.35	0.48
G	1.80	2.00
H	0.02	0.10
J	0.05	0.15
K	2.20	2.60

Mounting Pad Layout(unit:mm)

SOT-23



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